

ESD Model at Waterjet Deflash Process of Semiconductor Tapeless Leadframe Package

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Abstract—This paper presents an ESD (electrostatic discharge) model using Charged Device Model (CDM), Machine Model (MM), and with package electrical modeling, at waterjet deflash process.

Keywords— ESD; waterjet; charged device model; CO2 bubbler.

I. TRIBOCHARGING AT WATERJET STATION

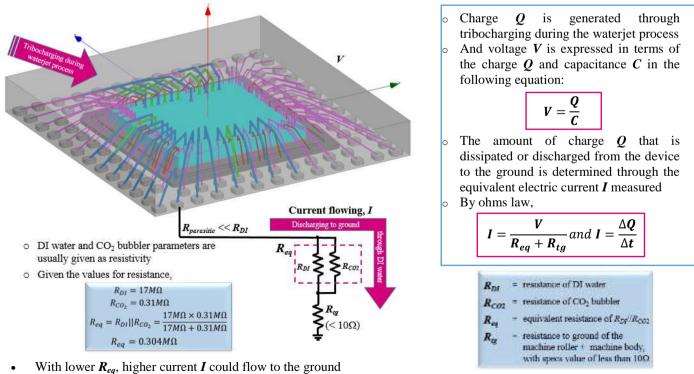
- Waterjet deflash process utilizes highly pressurized water to clean the metal lead surfaces of the semiconductor tapeless leadframe package
- Upon contact with the device, ESD through triboelectric charging or simply tribocharging happens due to fast frictional contact between the two materials
- Charges are dissipated from the unit passing through the DI water, onto the rollers, to the machine body, and onto the ground



Fig. 1. Waterjet deflash process illustrating the tribocharging.

II. ESD MODEL WITH PACKAGE MODELING

- ESD (electrostatic discharge) models namely Charged Device Model (CDM) + Machine Model (MM) could be used to illustrate the charged device with discharge path to the ground through the deionized (DI) water
- CO₂ bubbler is added to lower the DI water's resistivity, eventually minimizing the effect of tribocharging
- In CDM, it is assumed that the device, along with its parasitic RLC (resistance, inductance, capacitance), has already been charged-up during the waterjet deflash process



• Therefore, more amount of charge Q of the package or device could be discharged at a period of time

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